

AMENDMENTS TO THE CLAIMS

Claim 1 (Currently Amended) A polishing apparatus for polishing a workpiece, said polishing apparatus comprising:

a polishing unit including:

a polishing table having a polishing surface thereon; and

a top ring for pressing the workpiece against said polishing surface; and

a cleaning unit including:

a rotatable shaft configured to be vertically movable;

~~at least one~~ a plurality of holding mechanisms ~~mechanism~~ mounted to said rotatable shaft for detachably holding the workpiece; and

a plurality of cleaning devices disposed around said rotatable shaft for cleaning the workpiece which has been polished in said polishing unit.

Claim 2 (Original) The polishing apparatus according to claim 1, wherein said plurality of cleaning devices is disposed concentrically with said rotatable shaft.

Claim 3 (Withdrawn) The polishing apparatus according to claim 1, wherein said at least one holding mechanism comprises a vacuum chucking mechanism.

Claim 4 (Currently Amended) The polishing apparatus according to claim 1, wherein said ~~at least one~~ plurality of holding mechanisms ~~comprise mechanism~~ ~~comprises~~ a chucking member for holding a periphery of the workpiece.

Claim 5 (Cancelled)

Claim 6 (Withdrawn) A polishing apparatus for polishing a workpiece, said polishing apparatus comprising:

a plurality of polishing units, each of said polishing units including:

a polishing table having a polishing surface thereon;
a top ring for pressing the workpiece against said polishing surface; and
a moving mechanism for moving said top ring between a polishing position on said polishing surface and a workpiece receiving/delivering position;
a linear transferring mechanism for transferring the workpiece between a plurality of transferring positions including the workpiece receiving/delivering position;
a receiving/delivering mechanism disposed at the workpiece receiving/delivering position for receiving and delivering the workpiece between said linear transferring mechanism and said top ring;
and
a controller operable to operate said linear transferring mechanism so as to perform one of serial processing for a plurality of workpieces and parallel processing for a plurality of workpieces.

Claim 7 (Withdrawn) A substrate processing apparatus for processing a substrate, said substrate processing apparatus comprising:

a transferring mechanism for transferring the substrate, said transferring mechanism including:
chucking members for holding a periphery of the substrate;
at least one air cylinder to operate said chucking members, said at least one air cylinder having a valve member and cylinder chambers defined in said at least one air cylinder by said valve member; and
a suction device for evacuating one of said cylinder chambers, said one of said cylinder chambers being located on a side of said chucking members.

Claim 8 (New) The polishing apparatus according to claim 1, wherein the number of said plurality of cleaning devices is larger than the number of said plurality of holding mechanisms.